

## **ABSTRACT**

### **PACKAGE WAFER PROCESSING METHOD**

There is provided a package wafer processing method including a processing step of processing a package wafer along planned dividing lines by a laser beam irradiation unit and forming processing grooves in the package wafer. The processing step includes a deviation amount measurement step of detecting the processing groove and an exposed key pattern closest to the planned dividing line corresponding to the processing groove at a predetermined timing and measuring, as a deviation amount, the difference between the distance from the processing groove to the exposed key pattern and the distance that is registered in a registration step and is from the planned dividing line corresponding to the processing groove to the closest key pattern, a correction step of correcting the feed amount of an indexing feed mechanism according to the deviation amount, and an indexing feed step of carrying out indexing feed of a holding table and the laser beam irradiation unit relatively with the feed amount corrected in the correction step.

(Figure 4)